

Product End-of-Life Disassembly Instructions
Product Category: **Servers**
Marketing Name / Model
[List multiple models if applicable.]

HPE EL8000 Chassis

HPE EL8000 Chassis Manager

HPE e910 ProLiant 1U Blade

HPE e910 ProLiant 2U Blade

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by Directive 2012/19/EU of the European Parliament and of the Council on Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	5
Batteries	All types including standard alkaline and lithium coin or button style batteries	3
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	Depending on Power Supply	3 - AC 9 - DC
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	Depending on number of Fans	9
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Item Description	Notes	Quantity of items included in product
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Key	T15
Torx Screw Driver	T25
Torx Screw Driver	T30

3.0 Product Disassembly Process

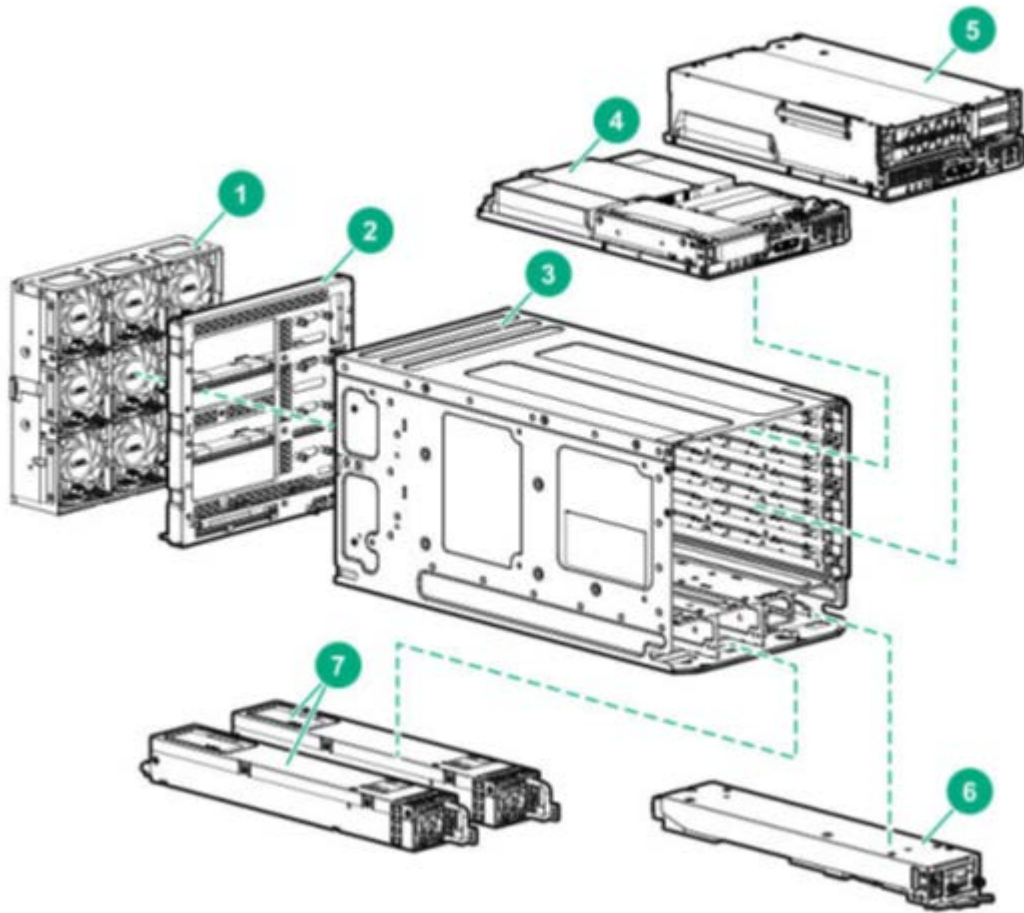
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Removing Blade- unlock using the T-15 Torx, Press and Open the Blade latch. Remove Blade server.
2. For 2U blade- Remove top cover. Remove Air Baffle for 1U and 2U. Remove DIMMs and options.
3. Loosen the heatsink nuts. Remove screw securing the system board. Locate Battery on system board. Remove battery and dispose of properly per selective treatment.
4. To remove power supply- press latch to unlock and slide power supply out. Remove cover and locate the large electrolytic caps needing selective treatment.
5. Locate the chassis manager module. To Remove- slide the retention latch. Press the release latch and remove.
6. Remove cover and locate Battery. Remove battery and dispose of properly per selective treatment

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

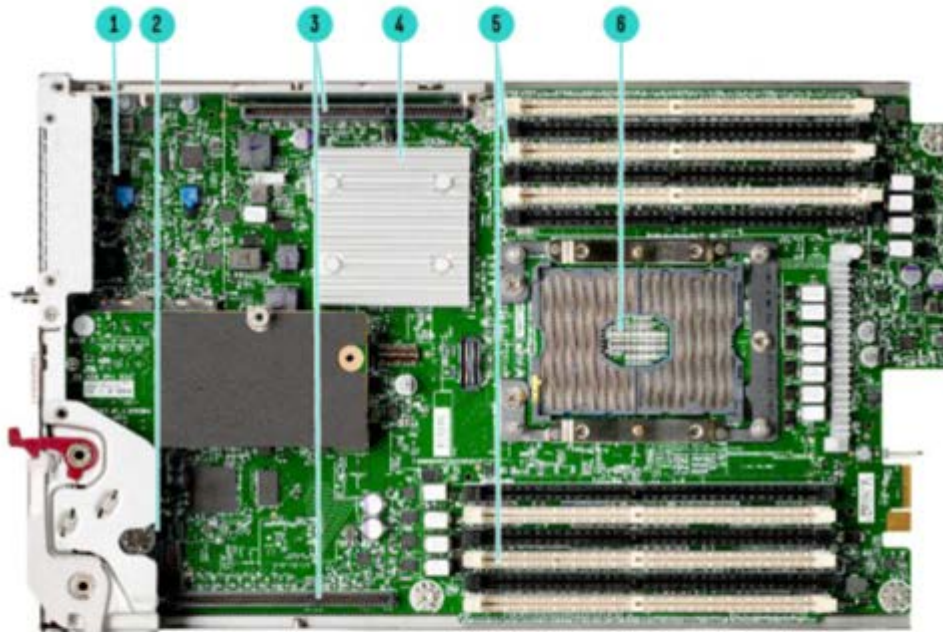
Pic 1- System components
Pic 2- e910 1U and 2U server blade
Pic 3- Battery location in e910 Blade and EL8000 Chassis manager & Storage Bay
Pic 4- Large Electrolytic caps in Power supply.

Pic1: System components



1. Fan Assembly
2. Midplane assembly
3. HPE Edgeline EL8000 Converged Edge Chassis
4. HPE ProLiant e910 1U server blade
5. HPE ProLiant e910 2U server blade
6. Chassis manager
7. Power supplies

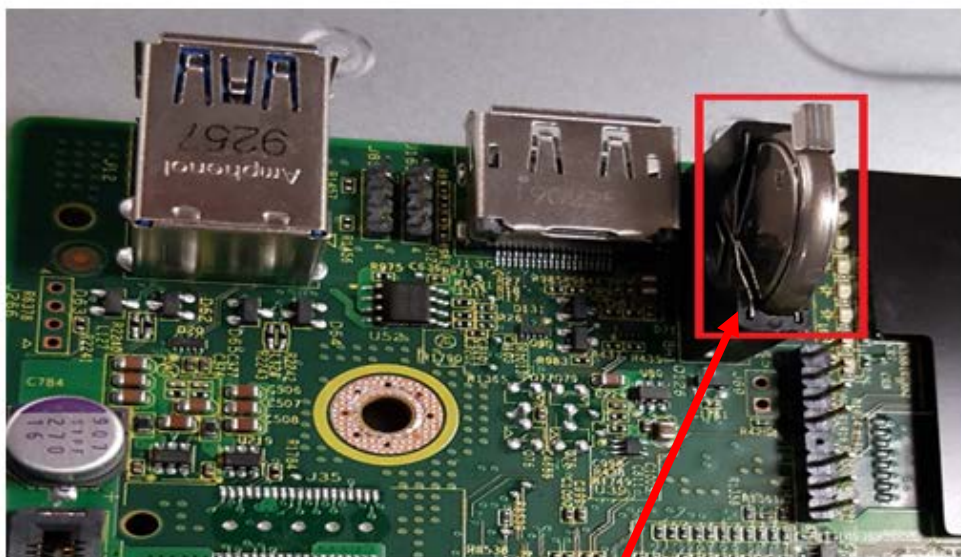
Pic2: ProLiant e910 1U and 2U Blade Server



1. M.2 SSD slots (Qty. 2 form factor 2242 or 2280)
2. System Battery
3. Left and Right PCIe Riser Slot\
4. Heatsink (Chipset)
5. DIMM slots (DDR4)
6. CPU Socket

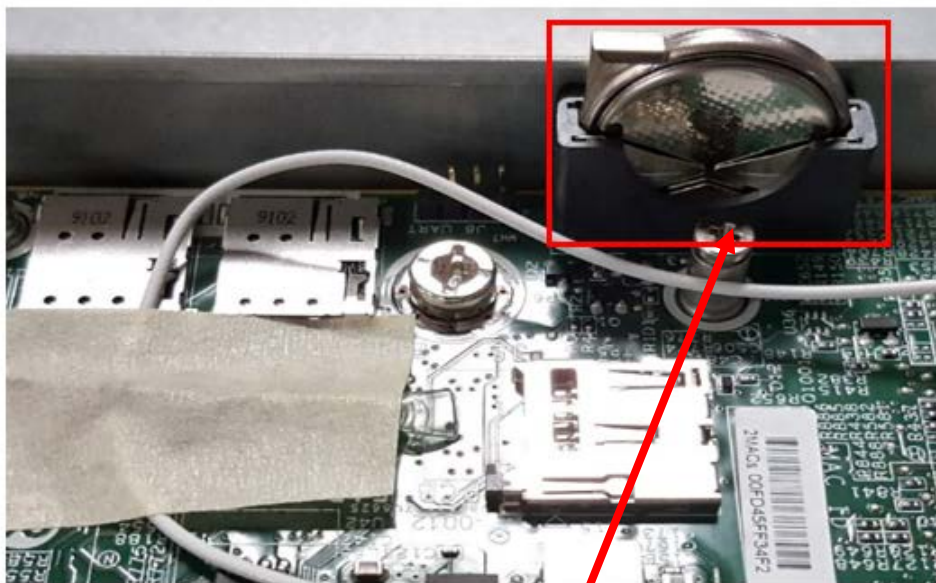
Pic 3: Batteries:

1. e910 ProLiant Blade:



Remove Battery

2. EL8000 Chassis Manager:



Remove Battery

3. EL8000 Storage Bay

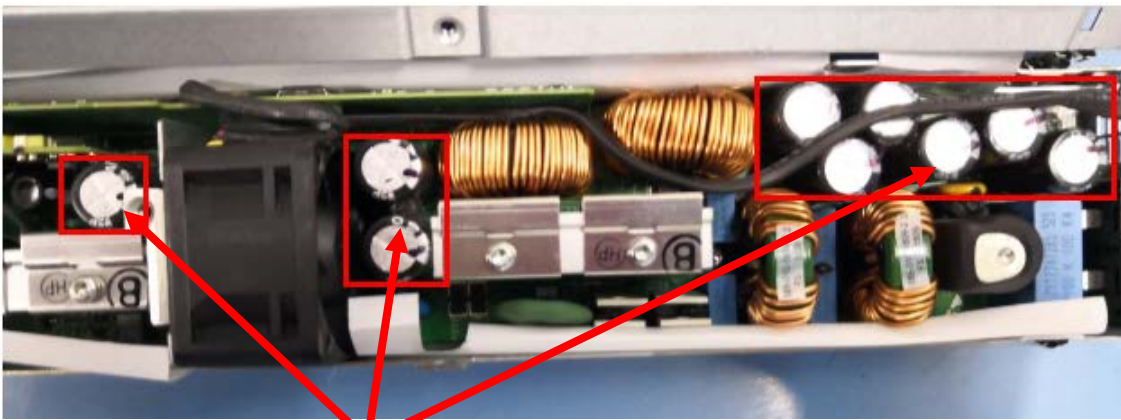


Remove Mega cell Battery

Pic4: Electrolytic Capacitors



Remove Capacitors



Remove Capacitors